

International Conference and Exhibition on Device Packaging

www.imaps.org/devicepackaging

**Radisson Fort McDowell Resort & Casino
Scottsdale/Fountain Hills, Arizona - USA
March 8 - 11, 2010**



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IMAPS**

**International Microelectronics And Packaging Society
Bringing Together the Entire Microelectronics Supply Chain!**

**Abstract Deadline Extended:
December 14, 2009**

Announcement and Call for Abstracts

Topical Workshop on

Emerging Technologies (LEDS & Passive Integration)

This workshop is being held as a part of the Device Packaging Conference

Emerging Technologies Technical Chairs:

LEDS

Chair: Frank Wall, Philips Lumileds Lighting Company
San Jose, CA 95131
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Passive Integration

Chair: Robert Heistand, AVX
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Organizing Committee:

David Saums, DS&A LLC
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Genevieve Martin, Philips Applied Technologies
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Grit Sommer, Infineon
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Courtesy of Philips Lighting Company

LED Devices Workshop Focus: The objective of the LED Devices Workshop is to have a unique forum that brings together scientists, engineers, manufacturing, academia, and business people from around the world who have been working in the area of LED Devices. This workshop has been specifically organized to allow for the presentation and discussion of some of the latest and hottest technologies related to packaging and applications of LED devices. **Abstracts are being requested on the following topics:**

- Industry Trends & Market Drivers in Solid State Lighting
- Integration, mounting, and assembly of packaged LEDs
- Electrical drivers, conversion efficiency, and color control of LEDs
- Active and passive thermal management techniques
- Materials for packaged LEDs
- Materials for carriers, substrates and interconnects
- Device attachment materials, processes, and equipment
- Manufacturing Trends & Techniques
- Optics and Lenses
- Discrete, array level Characterization and in-process testing, including imaging, void detection, stress/strain, high temperature measurement
- Reliability aspects of LED
- Intelligent system: control, dimming, energy management
- Architecture of system integration
- Applications, such as: Handheld, Medical, Avionics, Military, Signage, Commercial, Automotive, General Lighting



Photos above courtesy of IPDIA



Photos above courtesy of AVX

Passive Integration Workshop Focus: The Passive Integration workshop is a forum for all parties working on solving the issues of integration of passive components or features. This ranges from academic investigations of new materials and processes to recently commercialized products and processes. The workshop is focused on recent developments in design, materials, fabrication, test, and applications of passive integration for resistors, capacitors, inductors, varistors, fuses, and magnetics. **Abstracts are being requested on the following topics:**

- Industry Trends & Market Drivers in Passive Integration
- Designing for Passive Integration
- New Materials for Passive Integration
- Passive Integration for 3D Modules
- Passive Integration Processing Breakthroughs
- New Infrastructure for Passive Integration
- Assembly with Integrated Passive Components and Substrates
- Testing Strategies and Methods for Integrated Passives
- Novel Integrated Passive Components
- Applications for Passive Integration

Those wishing to present in the Emerging Technologies Workshop sector of the Device Packaging Conference must submit a 200-300 word abstract electronically **no later than December 14, 2009**, using the on-line submittal form at: www.imaps.org/abstracts.htm. No formal technical paper is required. A reproduction-ready two to six page concise summary with text (figures and graphs included if necessary) will be required for the abstract booklet on Friday, January 29, 2010. A post-conference CD containing the full presentation material as supplied by authors will be mailed 15 business days after the event to all attendees. Please contact Jackki Morris-Joyner by email at jmorris@imaps.org or by phone at 305-382-8433 if you have questions.

In addition, this year, the track Technical Chairs will be choosing select papers from the Conference for inclusion in a volume entitled "Advanced Microelectronic Packaging 2009". Participation is not mandatory, but we're sure many of you will want to participate in this highly exciting new concept. Papers not selected for this volume will, as always, have submission to the IMAPS online journal and submission to the annual IMAPS fall meeting as future options.

Device Packaging Exhibit and Technology Show: IMAPS will hold a concurrent exhibition for vendors and suppliers who support the many aspects of Emerging Technologies. This venue features an ideal atmosphere to showcase your products and services to key decision making professionals in the industry. Full 8' by 10' exhibit spaces will be available. To reserve booth space please fill out the on-line submittal form before February 4, 2010 at: www.imaps.org/devicepackaging or contact Ann Bell by email at abell@imaps.org or by phone at 202-548-8717.

Device Packaging Professional Development Courses (PDCs): For those wishing to broaden their knowledge of device packaging, a selection of half-day courses will be offered on Monday, March 8th, preceding the technical conference. If you would like to participate as an instructor, please submit a description of your short course to Jackki Morris-Joyner by email at jmorris@imaps.org **no later than December 14, 2009.**